Intel® Low Power Modules for Applied Computing

Product Highlights

Features:

- Pentium® III processor – Low Power 500 MHz with 256K L2 cache on die with front side bus speed of 100 MHz
- Pentium II processor – Low Power 333 MHz with 256K L2 cache on die with front side bus speed of 66 MHz
- Pentium II processor – Low Power 266 MHz with 512K SRAM L2 cache on board with front side bus speed of 66 MHz

Product Overview

The Intel® Low Power modules for Applied Computing are driving higher performance in embedded applications.

The configurations available are:

- Pentium III processor – Low Power module (with a 100 MHz PSB):
  - 500 MHz with 256K L2 cache on die
- Pentium II processor – Low Power modules (with a 66 MHz PSB):
  - 266 MHz with 512K SRAM L2 cache on board
  - 333 MHz with 256K L2 cache on die

These Low Power (LP) modules incorporate state-of-the-art technologies, like Intel's 0.25 micron manufacturing process for the Pentium II processor – Low Power based modules and 0.18 micron manufacturing process for the Pentium III processor – Low Power based module. They also feature Dual Independent Bus (DIB) architecture, for performance-hungry embedded applications in industries like communications, industrial automation and transaction terminals.

Product Description

The Low Power modules for applied computing combine voltage regulation, northbridge of the Intel® 440BX chipset with either:

- Pentium III processor – LP with 256K Level 2 cache on die operating at 500 MHz
- Pentium II processor – LP with 256K Level 2 cache on die (for module operating at 333 MHz)
- Pentium II processor – LP with 512K Level 2 cache on board (for Module operating at 266 MHz)

All these elements are integrated in a convenient printed circuit board unit.

The Pentium II processor-based module supports MMX™ technology. In addition the Pentium III processor-based module supports the Streaming SIMD Extension instruction set (SSE™). SSE enables a more visual experience for the end user and allows new applications such as real-time video encoding and speech recognition.

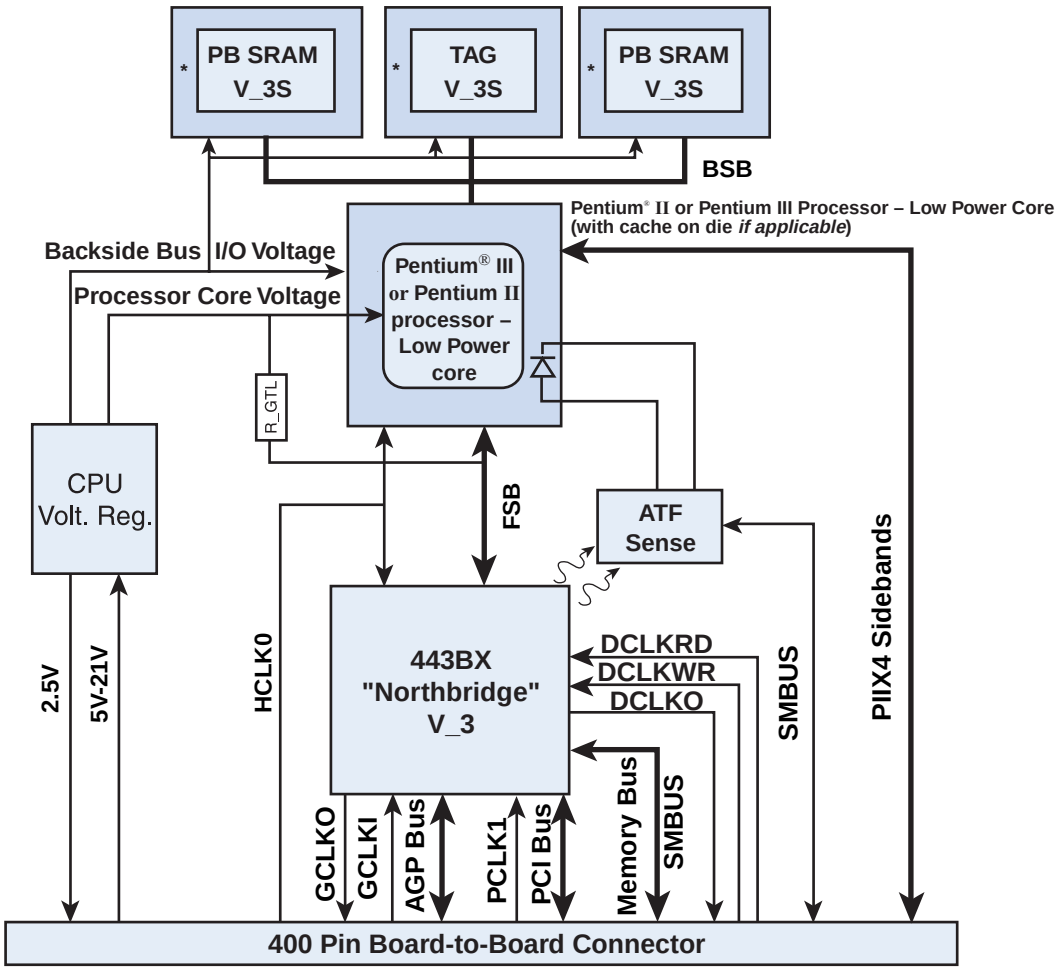
The Dual Independent Bus (DIB) architecture available in both the Pentium III processor and the Pentium II processor-based modules offers up to three times the bandwidth over single bus. By combining two independent system buses for simultaneous parallel access to data, the Pentium III processor – LP module and the Pentium II processor – LP modules provide an open road for high-demand embedded applications.

In addition, these processors feature Intel's Dynamic Execution Micro-Architecture. It combines three innovative data-processing techniques to manipulate data more intelligently and efficiently. These techniques predict and analyze software instructions to optimize processor workload.

The compact form factor of the Low Power Module results in a small space requirement while yielding a high level of performance. The module dimensions are 2-1/2" X 4", in a double-sided printed circuit board.

Intel® Pentium® III Processor – Low Power Module at 500 MHz with 256K L2 Cache On Die and 100 MHz FSB

* Applies only to Pentium® II Processor—Low Power Module with cache on board



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Order Number: 273193-004 Printed in USA/0301/IL10428E GA